

Amendments to the Specification:

Kindly amend the paragraph beginning on page 7, line 5 as shown.

-- Referring to FIGURE 4, there is shown a cross-sectional view of a solder joint between a lower pad 16 and an upper pad 29. As generally occurs in a soldering operation, ~~having an intermetallic region~~ regions are formed between within both solder 25 and the pad ~~10~~ 16, and an intermetallic boundary ~~15~~ boundaries 15' being formed therein is shown. ~~The pad 10 has~~ Upper and lower surfaces of pads 16 and 29, respectively, each have the serpentine solder configuration depicted in FIGURE 3a. It will be observed that the respective micro-cracking 20 at near each intermetallic boundary ~~15~~ 15' ~~is following~~ follows a circuitous or meandering path. The lengthening of the crack pathway increases the useful life of the solder joint. Other pad configurations are shown in FIGURES 3b through 3d. As before, ~~this results~~ these configurations result in micro-crack pathways that are interrupted, lengthened, or constrained. In a similar manner, these configurations are expected to increase fatigue life of the solder joint, as is that of the solder design shown in FIGURE 3a. --